

## Automotive power Schottky rectifier

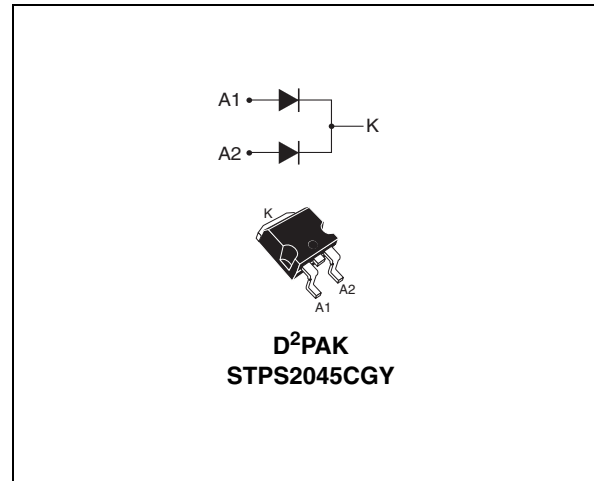
### Features

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Avalanche rated
- AEC-Q101 qualified

### Description

Dual center tap Schottky rectifier suited for high frequency DC to DC converters.

Packaged in D<sup>2</sup>PAK, this device is especially intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.



**Table 1. Device summary**

$I_{F(AV)}$	2 x 10 A
$V_{RRM}$	45 V
$T_{j(max)}$	175 °C
$V_{F(typ)}$	0.57 V

# 1 Characteristics

**Table 2. Absolute ratings (limiting values, per diode)**

Symbol	Parameter			Value	Unit	
$V_{RRM}$	Repetitive peak reverse voltage			45	V	
$I_{F(RMS)}$	Forward rms current			30	A	
$I_{F(AV)}$	Average forward current $\delta = 0.5$	$T_c = 155\text{ }^\circ\text{C}$	Per diode	10	A	
$I_{FSM}$	Surge non repetitive forward current			$t_p = 10\text{ ms}$ sinusoidal	180	A
$P_{ARM}$	Repetitive peak avalanche power			$t_p = 1\text{ }\mu\text{s}$ , $T_j = 25\text{ }^\circ\text{C}$	4000	W
$T_{stg}$	Storage temperature range			-65 to +175	$^\circ\text{C}$	
$T_j$	Maximum operating junction temperature <sup>(1)</sup>			-40 to +175	$^\circ\text{C}$	
$dV/dt$	Critical rate of rise of reverse voltage			10000	V/ $\mu\text{s}$	

1.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistances parameters**

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	2.2	$^\circ\text{C/W}$
		Total	1.3	
$R_{th(c)}$	Coupling		0.3	$^\circ\text{C/W}$

When the diodes 1 and 2 are used simultaneously :

$$T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

**Table 4. Static electrical characteristics (per diode)**

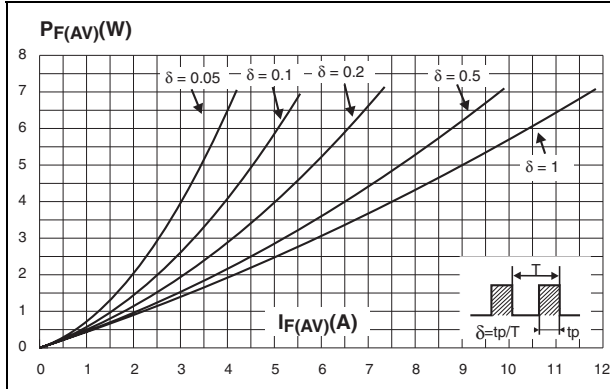
Symbol	Test conditions			Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ }^\circ\text{C}$	$V_R = V_{RRM}$	-	-	100	$\mu\text{A}$
		$T_j = 125\text{ }^\circ\text{C}$		-	7	15	mA
$V_F^{(1)}$	Forward voltage drop	$T_j = 125\text{ }^\circ\text{C}$	$I_F = 10\text{ A}$	-	0.5	0.57	V
		$T_j = 25\text{ }^\circ\text{C}$	$I_F = 20\text{ A}$	-	-	0.84	
		$T_j = 125\text{ }^\circ\text{C}$		-	0.65	0.72	

1. Pulse test :  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

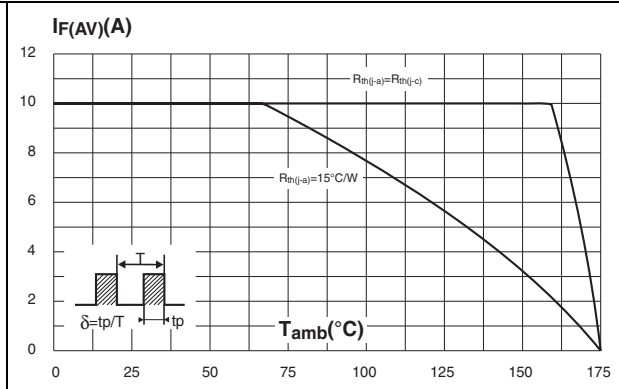
To evaluate the conduction losses use the following equation:

$$P = 0.42 \times I_{F(AV)} + 0.015 I_{F(RMS)}^2$$

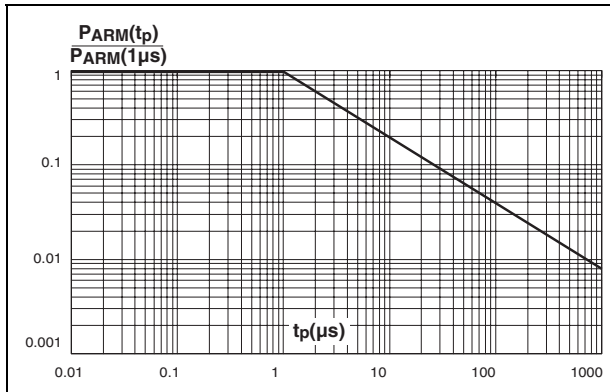
**Figure 1. Average forward power dissipation versus average forward current (per diode)**



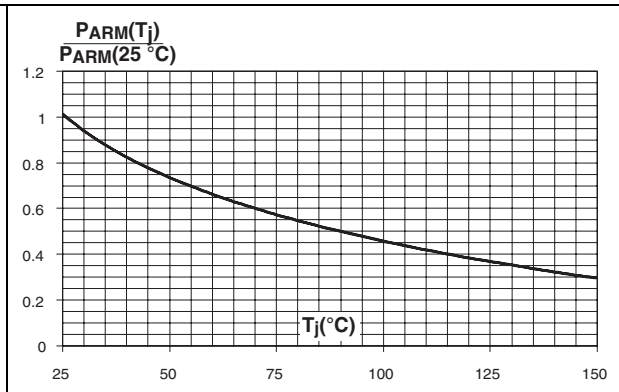
**Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ , per diode)**



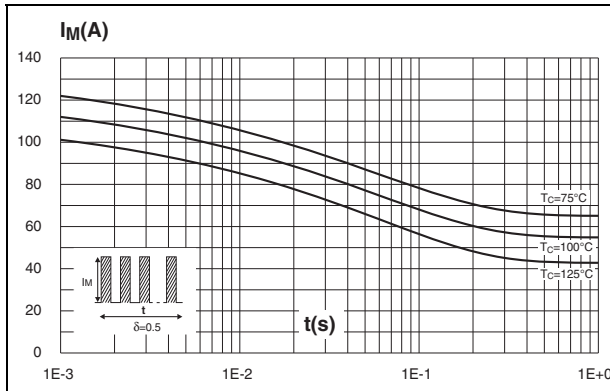
**Figure 3. Normalized avalanche power derating versus pulse duration**



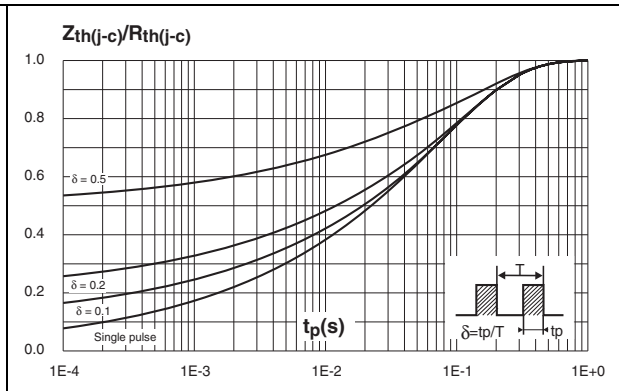
**Figure 4. Normalized avalanche power derating versus junction temperature**



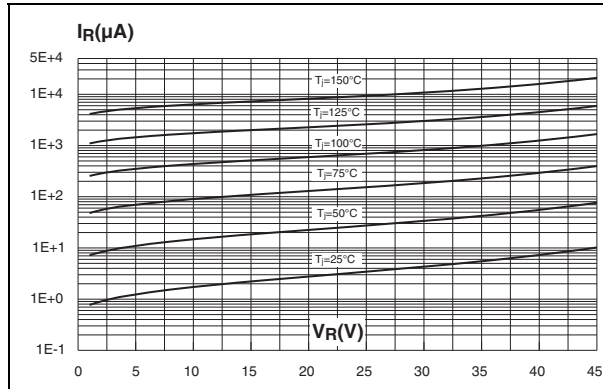
**Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)**



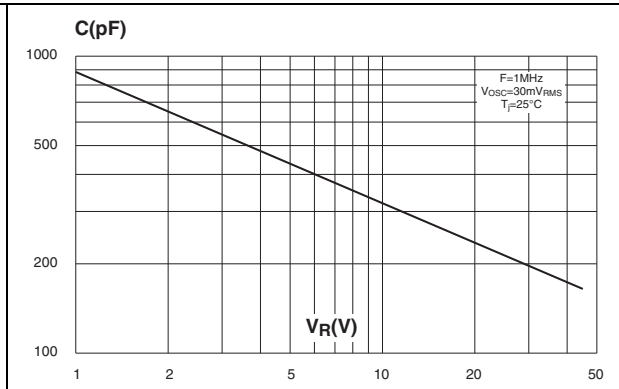
**Figure 6. Relative variation of thermal impedance junction to ambient versus pulse duration**



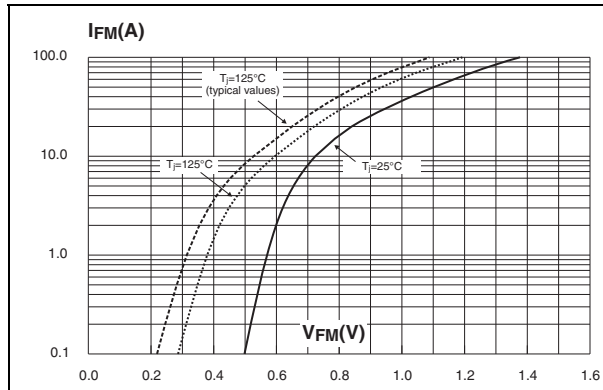
**Figure 7. Reverse leakage current versus reverse voltage applied (typical values, per diode)**



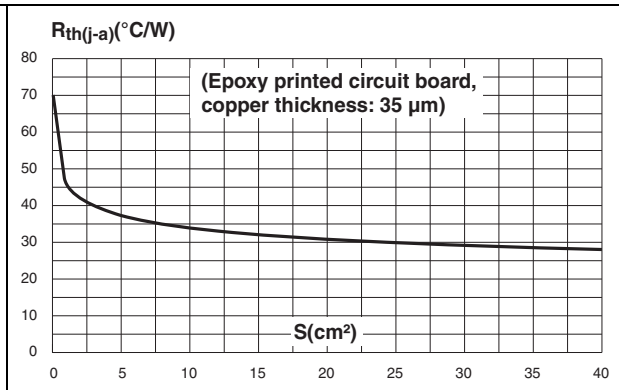
**Figure 8. Junction capacitance versus reverse voltage applied (typical values, per diode)**



**Figure 9. Forward voltage drop versus forward current (maximum values, per diode)**



**Figure 10. Thermal resistance junction to ambient versus copper surface under tab**



## 2 Package information

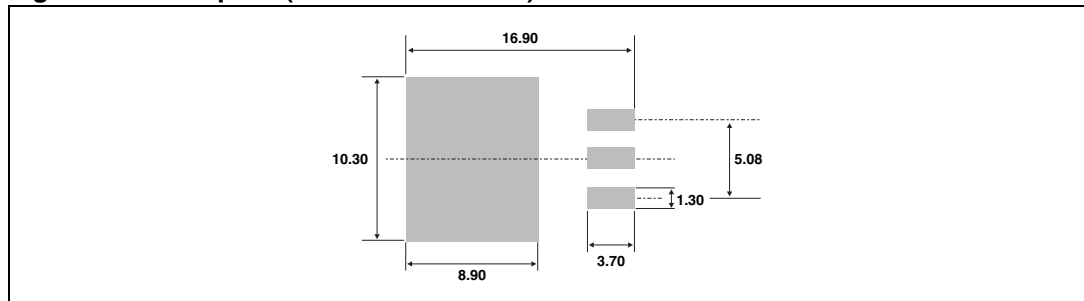
- Epoxy meets UL94, V0
- Lead-free package

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**Table 5. D<sup>2</sup>PAK dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

**Figure 11. Footprint (dimensions in mm)**



### 3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS2045CGY-TR	STPS2045CGY	D <sup>2</sup> PAK	1.48 g	1000	Tape and reel

### 4 Revision history

Table 7. Document revision history

Date	Revision	Changes
24-May-2011	1	Initial release.

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